

PATENT NUMBER

## U.S. REISSUE Patent Application

1226 O.I.P.E. SCANNED O.A.	O.G. PUBLICATION DATE 12/19/00	REISSUE PATENT DATE
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APPLICATION NO. 09/704529	CONT/PRIOR D F	CLASS 148 438	SUBCLASS 759	ART UNIT 2813 2823	EXAMINER L. Pham
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Wafer having chamfered bend portions in the joint regions between the contour of the wafer and the cut-away portion of the wafer

PTO-2040  
12/99

☒ SURRENDER OF ORIGINAL PATENT

(Ex. Initials)

**ORIGINAL PATENT NUMBER**

5,230,747

**ISSUING CLASSIFICATION**

[illegible]

Continued on Issue 518: Inside File Jacket

☐ **TERMINAL  
DISCLAIMER**

## DRAWINGS

**CLAIMS ALLOWED**

**Sheets Drwg.**

**Figs. Drwg.**

Print Fig.

Total Claims

Print Claim for O.G.

9

17

7.8

3

1

☐ The term of this patent subsequent to \_\_\_\_\_ (date) has been disclaimed.

☐ The term of this patent shall not extend beyond the expiration date of U.S. Patent. No. \_\_\_\_\_

☐ The terminal \_\_\_\_ months of this patent have been disclaimed.

(Assistant Examiner)

(Date \_\_\_\_\_)

LONG PHAM  
PRIMARY EXAMINER

(Primary Examiner)

(Date \_\_\_\_\_)

## FINAL SPRE REVIEW

**ISSUE BATCH NUMBER**

(INITIALS)

(Legal Instruments Examiner)

(Date \_\_\_\_\_)

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